

**FLASH-PREVENTING WINDOW BALL GRID ARRAY SEMICONDUCTOR
PACKAGE, METHOD FOR FABRICATING THE SAME, AND CHIP
CARRIER USED IN THE SEMICONDUCTOR PACKAGE**

ABSTRACT

A flash-preventing window ball grid array semiconductor package, a method for fabricating the same, and a chip carrier used in the semiconductor package are provided. The chip carrier has a through hole and has a surface formed with a plurality of wire-bonding portions, ball-bonding portions and intended-exposing regions. A chip is mounted over the through hole and electrically connected to the wire-bonding portions by a plurality of bonding wires penetrating through the through hole. An encapsulation body encapsulates the chip and bonding wires. The intended-exposing regions serve as a narrow runner which is filled with an encapsulating material forming the encapsulation body, making the encapsulating material not flash over the ball-bonding portions. This allows a plurality of solder balls to be well bonded to the ball-bonding portions, thereby assuring the quality of electrical connection and the surface planarity of the semiconductor package.

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